Silicon P-Channel MOS FET

HITACHI

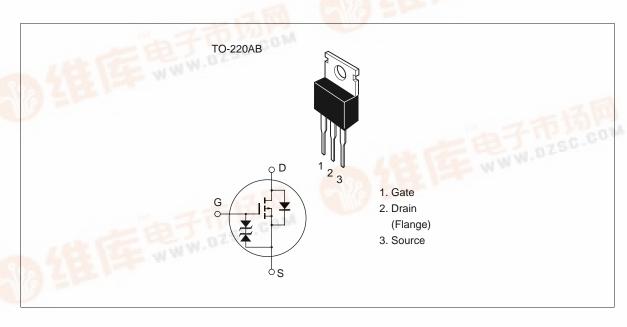
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-100	V	
Gate to source voltage	$V_{\sf GSS}$	±20	V	
Drain current	I _D	-20	А	
Drain peak current	I _{D(pulse)} *1	-80	Α	
Body to drain diode reverse drain current	I_{DR}	-20	Α	
Channel dissipation	Pch*2	75	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

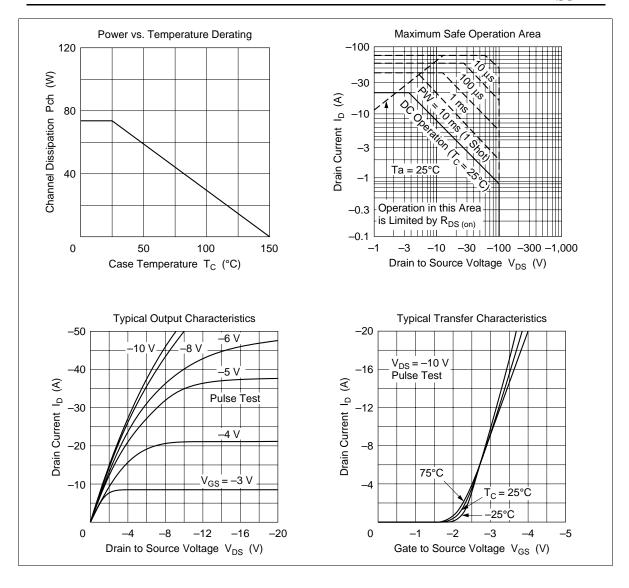
Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

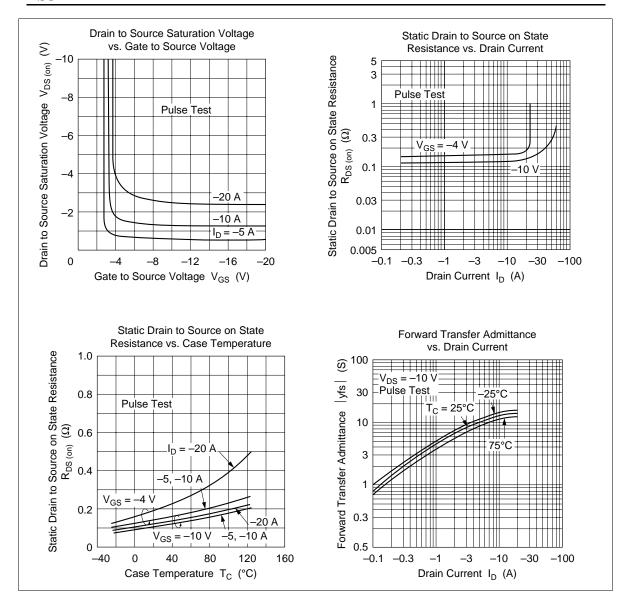
2. Value at $T_c = 25^{\circ}C$

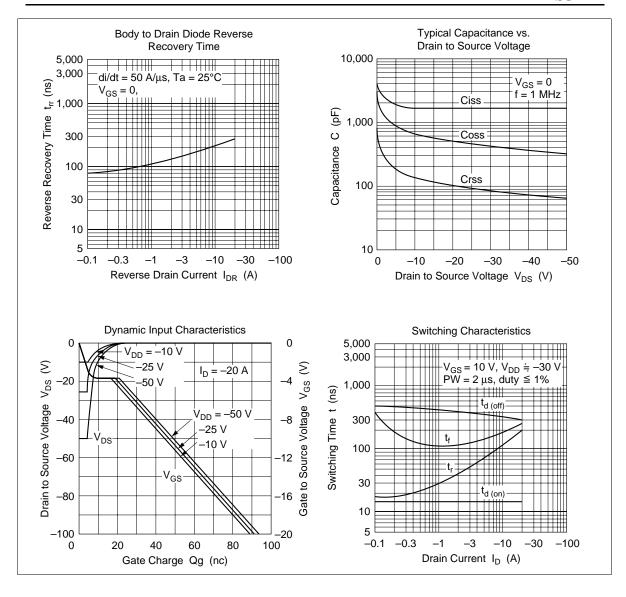
Electrical Characteristics ($Ta = 25^{\circ}C$)

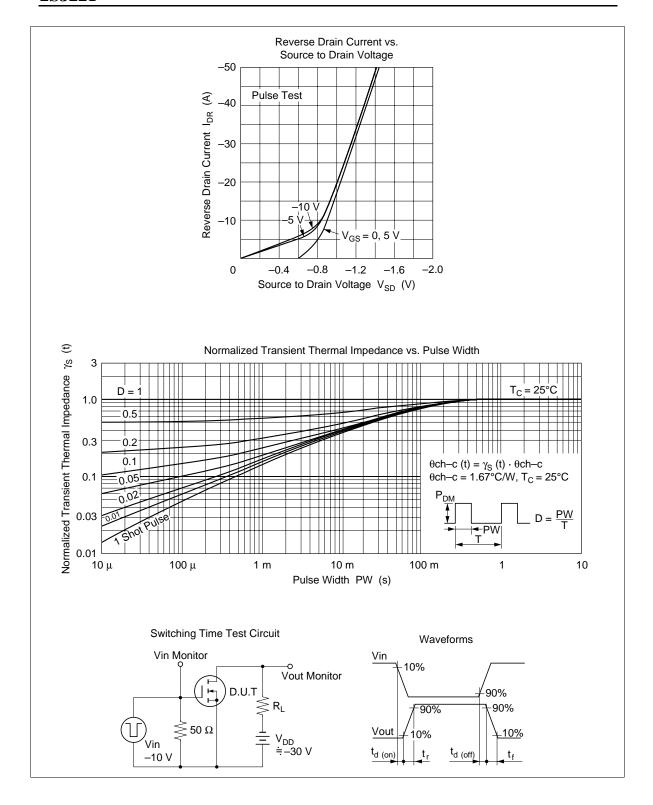
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-100	_	_	V	$I_{D} = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	-250	μΑ	$V_{DS} = -80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-1.0	_	-2.0	V	$I_{D} = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.12	0.16	Ω	$I_D = -10 \text{ A}, V_{GS} = -10 \text{ V}^{*1}$
resistance		_	0.16	0.22		$I_D = -10 \text{ A}, V_{GS} = -4 \text{ V}^{*1}$
Forward transfer admittance	y _{fs}	7.5	12	_	S	$I_D = -10 \text{ A}, V_{DS} = -10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1800	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	680	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	145	_	pF	
Turn-on delay time	$\mathbf{t}_{\text{d(on)}}$	_	15	_	ns	$I_D = -10 \text{ A}, V_{GS} = -10 \text{ V},$
Rise time	t _r	_	115	_	ns	$R_L = 3 \Omega$
Turn-off delay time	$t_{\text{d(off)}}$	_	320	_	ns	
Fall time	t _f	_	170	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.05	_	V	$I_F = -20 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	280	_	ns	$I_F = -20 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu\text{s}$
Note: 1 Bules test						

Note: 1. Pulse test

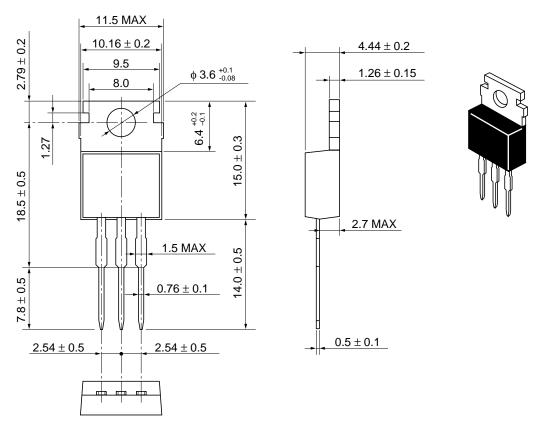












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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany

Tel: <49 > (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office

3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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